



ECH8651R — General-Purpose Switching Device Applications

N-Channel Silicon MOSFET

Features

- Low ON-resistance
- 2.5V drive
- Common-drain type
- Protection diode in
- Built-in gate protection resistor
- Best suited for LiB charging and discharging switch
- Halogen free compliance

Specifications

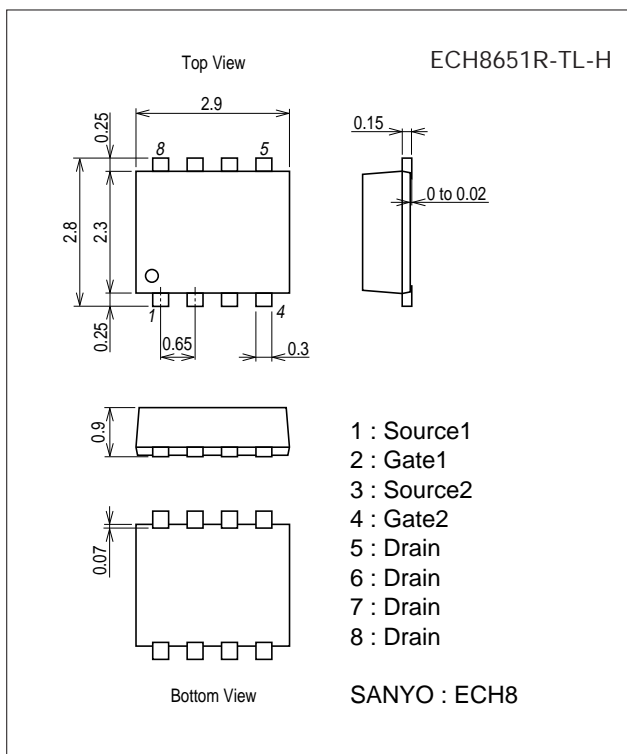
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	V _{DSS}		24	V
Gate-to-Source Voltage	V _{GSS}		±12	V
Drain Current (DC)	I _D		10	A
Drain Current (Pulse)	I _{DP}	PW≤10μs, duty cycles≤1%	60	A
Allowable Power Dissipation	P _D	When mounted on ceramic substrate (900mm ² ×0.8mm) 1unit	1.4	W
Total Dissipation	P _T	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.5	W
Channel Temperature	T _{ch}		150	°C
Storage Temperature	T _{stg}		-55 to +150	°C

Package Dimensions

unit : mm (typ)

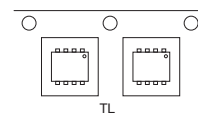
7011A-003



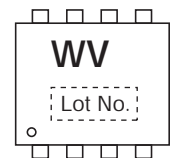
Product & Package Information

- Package : ECH8
- JEITA, JEDEC : -
- Minimum Packing Quantity : 3,000 pcs./reel

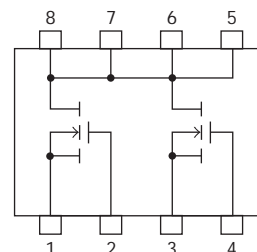
Packing Type : TL



Marking



Electrical Connection

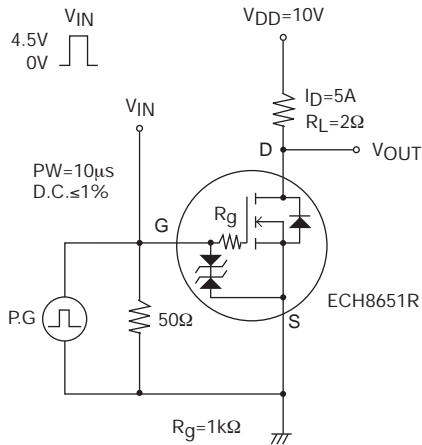


ECH8651R

Electrical Characteristics at $T_a=25^\circ\text{C}$

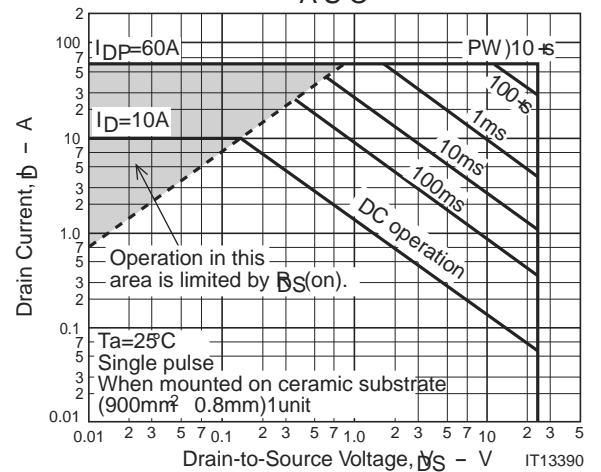
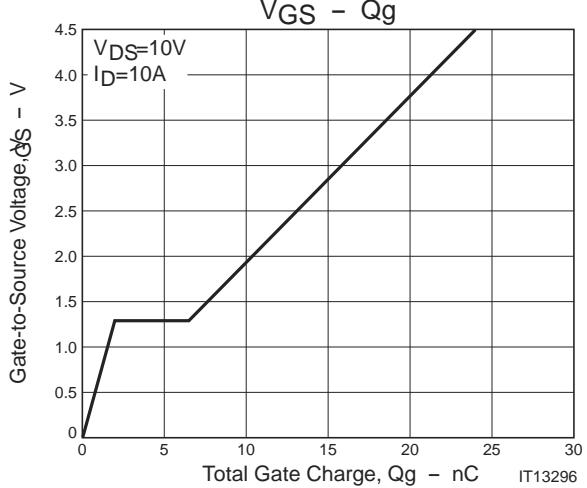
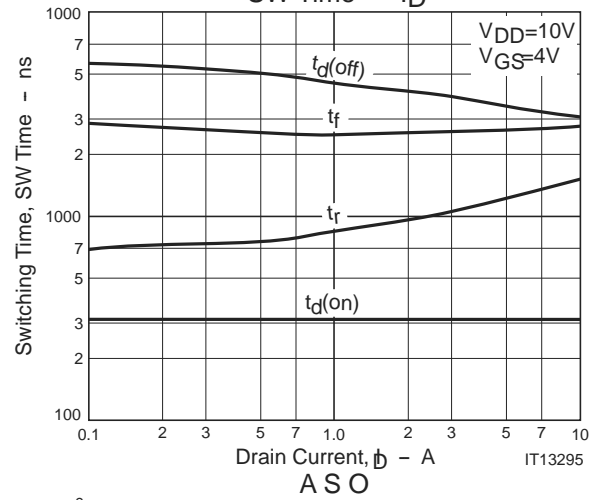
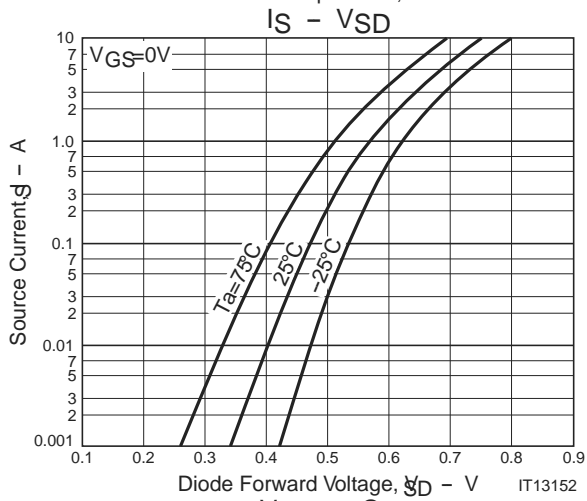
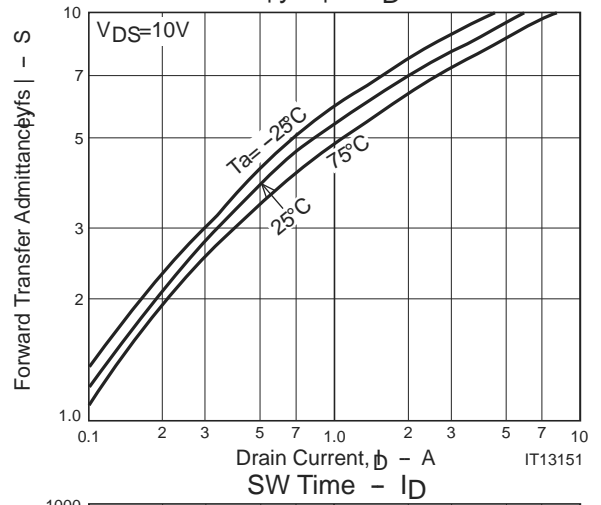
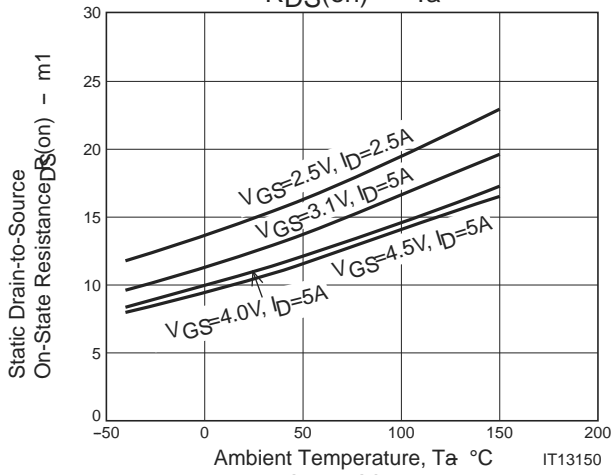
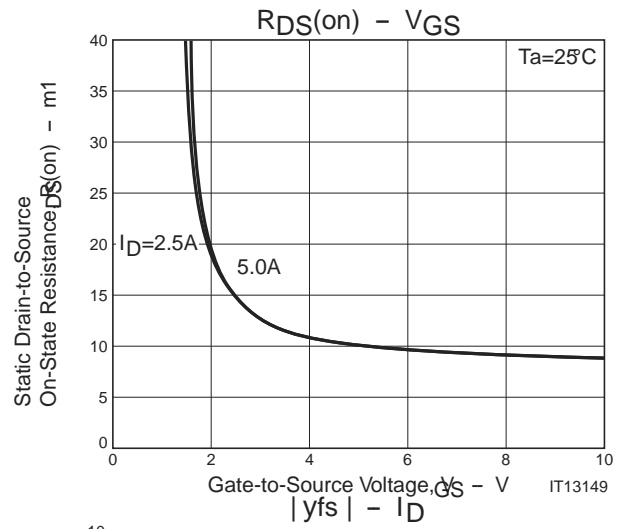
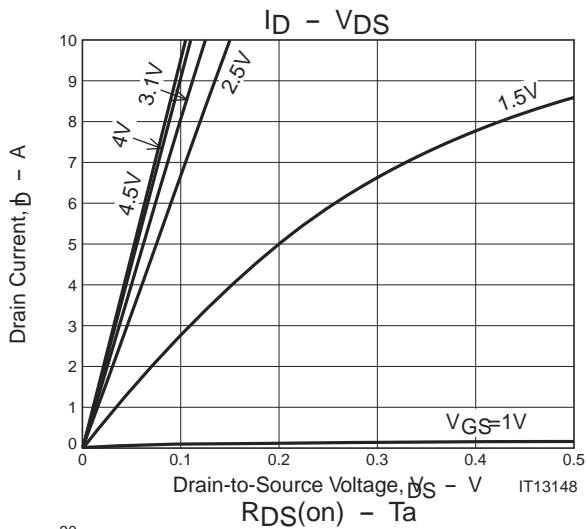
Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D=1\text{mA}$, $V_{GS}=0\text{V}$	24			V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$			1	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 8\text{V}$, $V_{DS}=0\text{V}$			± 10	μA
Cutoff Voltage	$V_{GS(off)}$	$V_{DS}=10\text{V}$, $I_D=1\text{mA}$	0.5		1.3	V
Forward Transfer Admittance	$ y_{fs} $	$V_{DS}=10\text{V}$, $I_D=5\text{A}$	5.5	9.5		S
Static Drain-to-Source On-State Resistance	$R_{DS(on)1}$	$I_D=5\text{A}$, $V_{GS}=4.5\text{V}$	7	10.5	14	$\text{m}\Omega$
	$R_{DS(on)2}$	$I_D=5\text{A}$, $V_{GS}=4.0\text{V}$	7.2	11	15	$\text{m}\Omega$
	$R_{DS(on)3}$	$I_D=5\text{A}$, $V_{GS}=3.1\text{V}$	7.5	12.5	17.5	$\text{m}\Omega$
	$R_{DS(on)4}$	$I_D=2.5\text{A}$, $V_{GS}=2.5\text{V}$	9	15	21	$\text{m}\Omega$
Turn-ON Delay Time	$t_{d(on)}$	See specified Test Circuit.		300		ns
Rise Time	t_r			1000		ns
Turn-OFF Delay Time	$t_{d(off)}$			4000		ns
Fall Time	t_f			2500		ns
Total Gate Charge	Q_g			24		nC
Gate-to-Source Charge	Q_{gs}	$V_{DS}=10\text{V}$, $V_{GS}=10\text{V}$, $I_D=10\text{A}$		2		nC
Gate-to-Drain "Miller" Charge	Q_{gd}			4.5		nC
Diode Forward Voltage	V_{SD}		$I_S=10\text{A}$, $V_{GS}=0\text{V}$		0.77	1.2

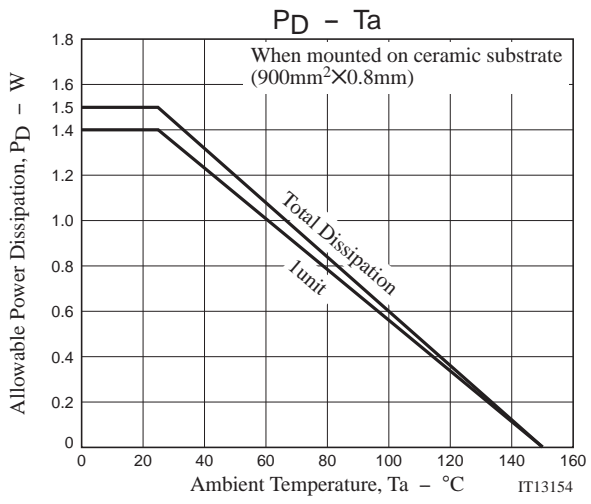
Switching Time Test Circuit



Ordering Information

Device	Package	Shipping	memo
ECH8651R-TL-H	ECH8	3,000pcs./reel	Pb Free and Halogen Free





ECH8651R

Embossed Taping Specification

ECH8651R-TL-H

1. Packing Format

Package Name	Carrier Tape Type	Maximum Number of devices contained (pcs)			Packing format	
		Reel	Inner box	Outer box	Inner BOX (C-1)	Outer BOX (A-7)
ECH8	CPH6	3,000	15,000	90,000	5 reels contained Dimensions:mm (external) 183×72×185	6 inner boxes contained Dimensions:mm (external) 440×195×210

Reel label, Inner box label
(unit :mm)

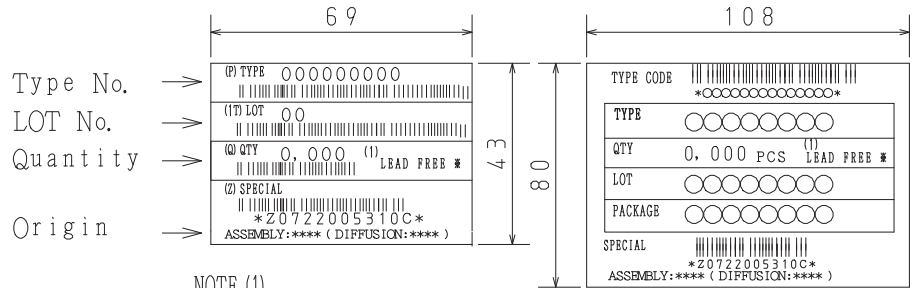
Outer box label

It is a label at the time of factory shipments.
The form of a label may change in physical distribution process.

Packing method



Reel label



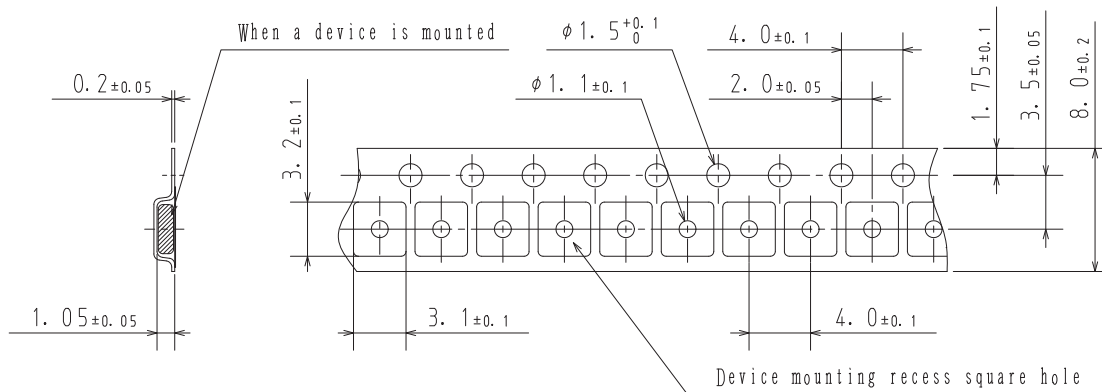
NOTE (1)

The LEAD FREE * description shows that the surface treatment of the terminal is lead free.

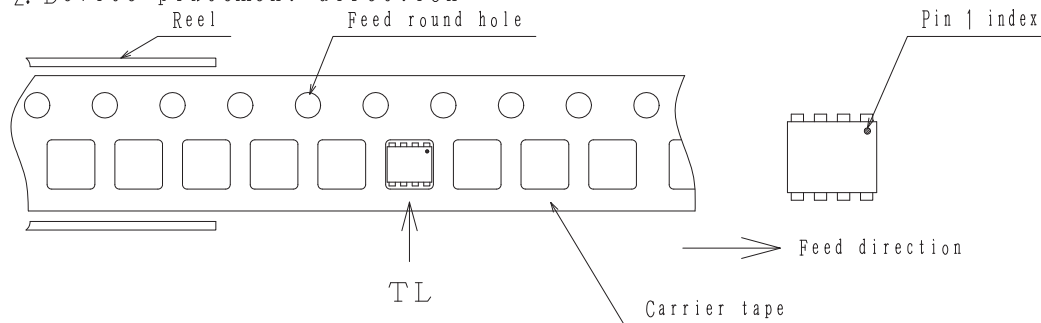
Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3

2. Taping configuration

2-1. Carrier tape size (unit:mm)



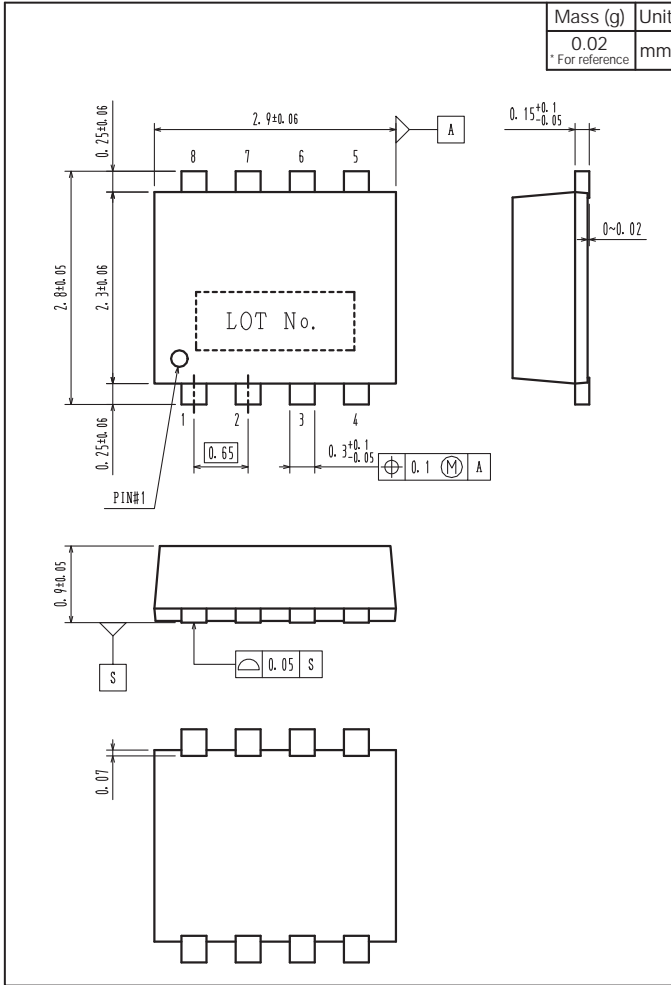
2-2. Device placement direction



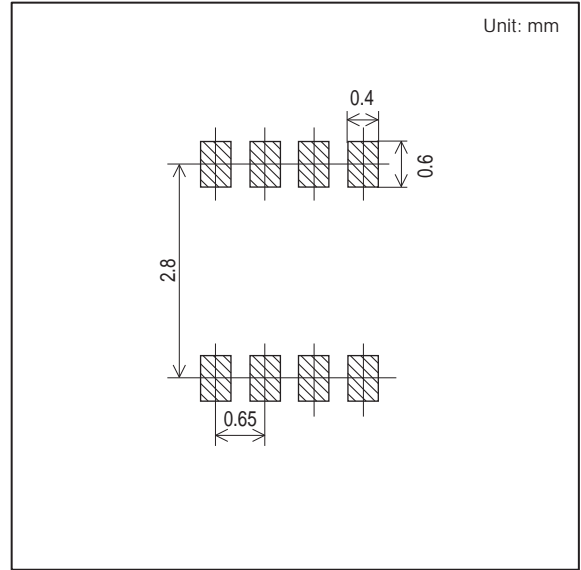
Those with pin 1 index on the feed hole side.....TL

ECH8651R

Outline Drawing ECH8651R-TL-H



Land Pattern Example



Note on usage : Since the ECH8651R is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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